

KD2310-VB Datasheet N-Channel 60-V (D-S) MOSFET

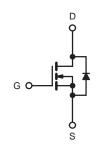
PRODUCT SUMMARY					
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)		
60	0.075 at V _{GS} = 10 V	4.0	2.1 nC		
00	0.086 at V _{GS} = 4.5 V	3.8	2.1110		

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- Trench Power MOSFET 100 % R_g Tested
- •
- 100 % UIS Tested •

APPLICATIONS

- Battery Switch
- DC/DC Converter



TO-236 (SOT23) G 1 3 D S 2 Top View

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_A = 2$	25 °C, unless oth	erwise noted			
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	60	V	
Gate-Source Voltage		V _{GS}	± 20	V	
	T _C = 25 °C		4.0		
Continuous Drain Current (T ₁ = 150 °C)	T _C = 70 °C	I_	3.4		
Continuous Drain Current (1j = 130°C)	T _A = 25 °C	I _D	3.1 ^{b, c}		
	T _A = 70 °C		2.5 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	12		
Continuous Source-Drain Diode Current	T _C = 25 °C	la la	1.39		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	0.91 ^{b, c}		
Avalanche Current		I _{AS}	6		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	1.8	mJ	
	T _C = 25 °C		1.66		
Maximum Rowar Dissipation	T _C = 70 °C	PD	1.06	W	
Maximum Power Dissipation	T _A = 25 °C	'D	1.09 ^{b, c}	v	
	T _A = 70 °C		0.7 ^{b, c}		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient ^{b, d}	≤ 5 s	R _{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	60	75	C/VV

Notes:

a. Based on T_C = 25 °C. b. Surface Mounted on 1" x 1" FR4 board.

c. t = 5 s.

d. Maximum under Steady State conditions is 120 °C/W.



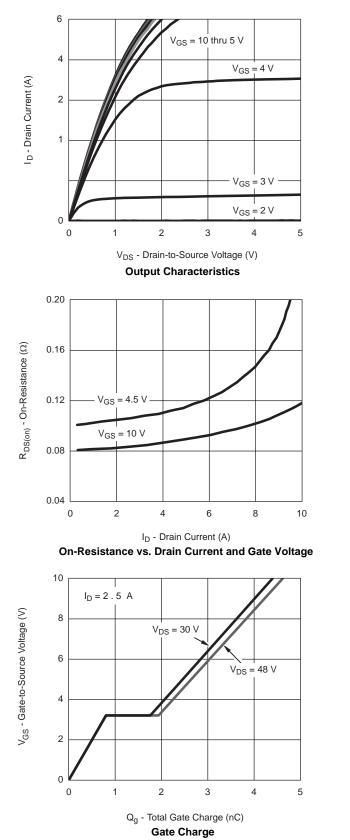
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	L 050 vA		55		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA		- 5			
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	1		3	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
Zara Cata Valtaga Drain Current	la a a	$V_{DS} = 60 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, \text{ V}_{GS}$ = 10 V	8			А	
	Р	V _{GS} = 10 V, I _D = 1.9 A		0.075		0	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 1.7 \text{ A}$		0.086		Ω	
Forward Transconductance ^a	9 _{fs}	V _{DS} = 15V, I _D = 1.9 A		5		S	
Dynamic ^b					•		
Input Capacitance	C _{iss}			180			
Output Capacitance	C _{oss}			22		_	
Reverse Transfer Capacitance	C _{rss}	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$		13		pF	
Tatal Cata Channa	Qg	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 1.9 \text{ A}$		4.2	6.1	nC	
Total Gate Charge				2.1	3.2		
Gate-Source Charge	Q _{gs}	$V_{DS} = 30$ V, $V_{GS} = 4.5$ V, $I_{D} = 1.9$ A		0.7			
Gate-Drain Charge	Q _{gd}			1			
Gate Resistance	Rg	f = 1 MHz	0.6	2.2	5.1	Ω	
Turn-On Delay Time	t _{d(on)}			4	6		
Rise Time	t _r	V_{DD} = 30 V, R_L = 20 Ω		10	15	- ns	
Turn-Off Delay Time	t _{d(off)}	$\text{I}_\text{D}\cong$ 1.5 A, V_GEN = 10 V, R_G = 1 Ω		10	15		
Fall Time	t _f			7	10.5		
Turn-On Delay Time	t _{d(on)}			15	23		
Rise Time	t _r	V_{DD} = 30 V, R_{L} = 20 Ω		16	24	- ns	
Turn-Off Delay Time	t _{d(off)}	I_{D} = 1.5 A, V_{GEN} = 4.5 V, R_{G} = 1 Ω		11	17		
Fall Time	t _f			11	17		
Drain-Source Body Diode Characteristic	cs				I		
Continuous Source-Drain Diode Current	۱ _S	T _C = 25 °C			2.19	٨	
Pulse Diode Forward Current ^a	I _{SM}				7		
Body Diode Voltage	V _{SD}	I _S = 1.5 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			15	23	ns	
Body Diode Reverse Recovery Charge	Q _{rr}			10	15	nC	
Reverse Recovery Fall Time	ta	I _F = 1.5 A, dl/dt = 100 A/μs, T _J = 25 °C		12		1	
Reverse Recovery Rise Time	t _b			3		ns	

Notes:

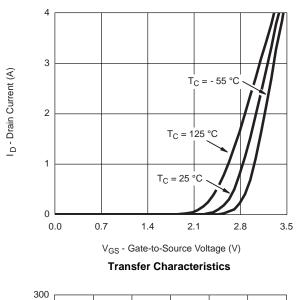
a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. b. Guaranteed by design, not subject to production testing.

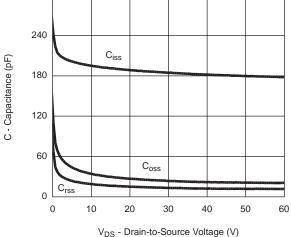
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



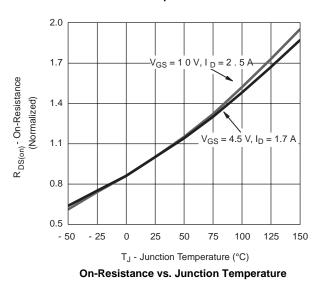


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



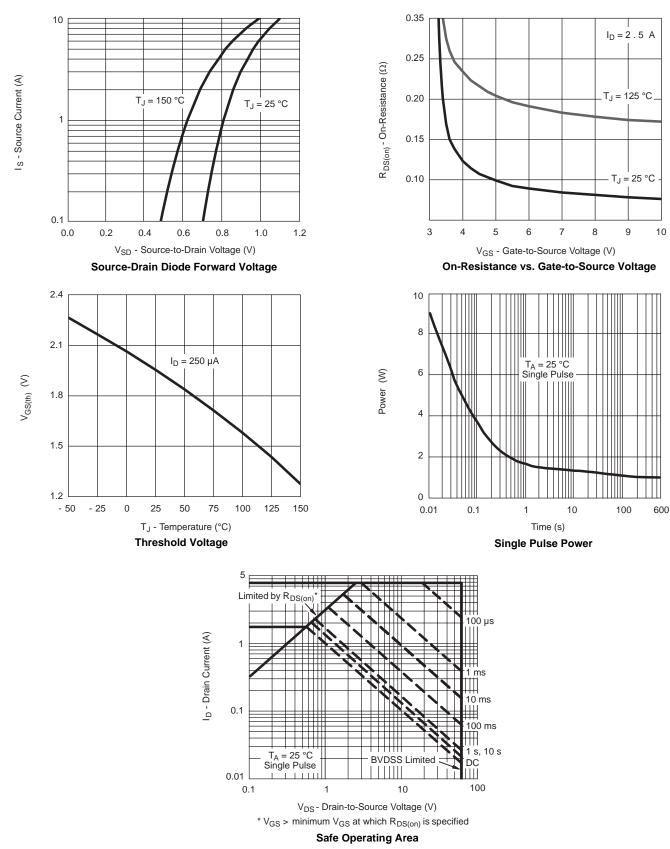


Capacitance





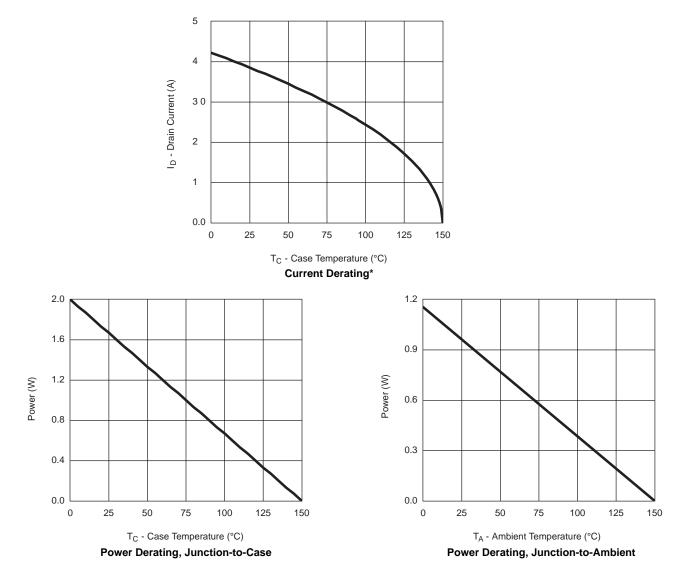
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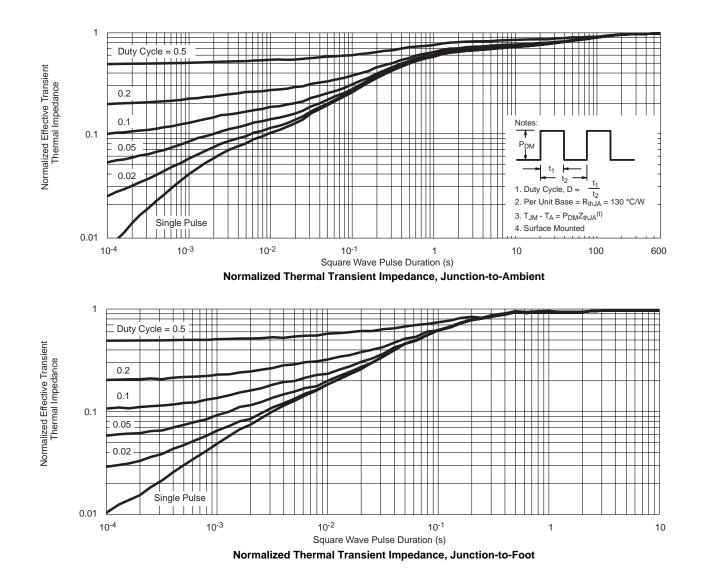


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



* The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



SOT-23 (TO-236): 3-LEAD







Dim –	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e ₁	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	



RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)



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